

MADL-011173-DIE

Rev. V1

Features

- Low Insertion Loss: < 0.5 dB
- Return Loss: > 20 dB
- Handles 41 dBm CW Power
- Low Flat Leakage Power: < 18 dBm
- Die Size: 2.79 x 2.64 mm
- RoHS* Compliant
- Passive Device

Applications

- ISM
- Multi Market
- Radar
- EW

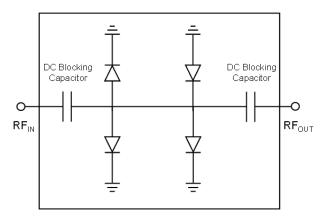
Description

The MADL-011173-DIE is an integrated AlGaAs PIN Diode limiter. It is a passive device, DC blocked at both the input and output ports.

The limiter is ideally designed to provide low insertion loss, at zero bias, as well as low flat leakage power with fast signal response/recovery times. It can limit up to 41 dBm incident CW power at room temperature. It is available in die form with a compact die dimension of 2.79 x 2.64 mm.

The MADL-011173 PIN limiter is designed for use in passive limiter control circuits to protect sensitive receiver components such as low noise amplifiers (LNA), detectors, and mixers.

Functional Schematic



Pin Configuration

Pin #	Pin Name	Description	
1	RF _{IN}	RF Input	
2	RF _{OUT}	RF Output	
3 - 6	GND	GND	

Ordering Information

Part Number	Package		
MADL-011173-DIE	Die in Gel Pack		

* Restrictions on Hazardous Substances, compliant to current RoHS EU directive.

1

MACOM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit <u>www.macom.com</u> for additional data sheets and product information.



MADL-011173-DIE

Rev. V1

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Insertion Loss	P _{IN} = -10 dBm 2 GHz 4 GHz	dB	—	0.5	0.7 0.8
Input Return Loss	P _{IN} = -10 dBm 2 - 4 GHz	dB	_	20	_
Output Return Loss	P _{IN} = -10 dBm 2 - 4 GHz	dB	—	20	_
Max CW Incident Power	2 - 4 GHz	dBm	—	41	_
CW Flat Leakage	P _{IN} > 27 dBm 2 GHz 4 GHz	dBm	_	15	16 15
Spike Leakage Power	P _{IN} = 42 dBm, 100 µs, 1% DC 2 - 4 GHz	dBm		16	_
Recovery Time (1dB Insertion Loss)	P _{IN} = 42 dBm, 100 µs, 1% DC 2 - 4 GHz	ns		80	_
Input IP3	10 MHz Offset, P _{IN} /tone = 0 dBm	dBm	_	33	_

Electrical Specifications: $T_A = 25^{\circ}C$, $Z_0 = 50 \Omega$

Absolute Maximum Ratings^{1,2}

Parameter	Absolute Maximum		
Incident CW RF Power at +25°C	41.3 dBm		
Peak Incident Power 1 µs pulse, 1% D.C. at +25°C	45 dBm		
Junction Temperature ³	+150°C		
Operating Temperature	-40°C to +85°C		
Storage Temperature	-55°C to +150°C		

1. Exceeding any one or combination of these limits may cause permanent damage to this device.

MACOM does not recommend sustained operation near these survivability limits.

3. Operating at nominal conditions with $T_J \le +150^{\circ}$ C will ensure MTTF > 1 x 10⁶ hours.

Handling Procedures

The protective polymer coating on the active areas of the die provides scratch and impact protection, particularly for the metal air bridge, which contacts the diode's anode. Die should primarily be handled with vacuum pickup tools, or alternatively with plastic tweezers.

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM Class 1B devices.

MACOM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit <u>www.macom.com</u> for additional data sheets and product information.

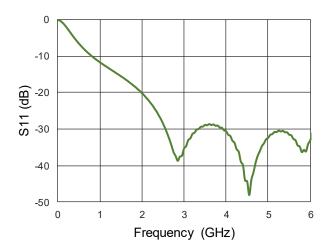


MADL-011173-DIE Rev. V1

Typical Small-Signal Performance, Die On-Wafer: $T_A = 25^{\circ}C$, $Z_0 = 50 \Omega$

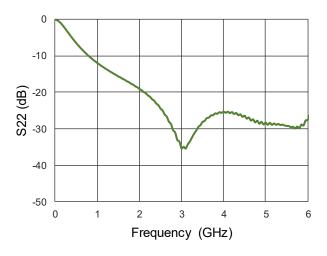
0.0 -0.2 -0.4 -0.6 S21 (dB) -0.8 -1.0 -1.2 -1.4 -1.6 0 1 2 3 4 5 6 Frequency (GHz)

Input Return Loss



Output Return Loss

Insertion Loss

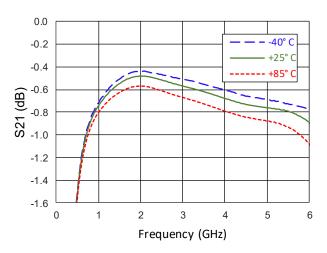


3

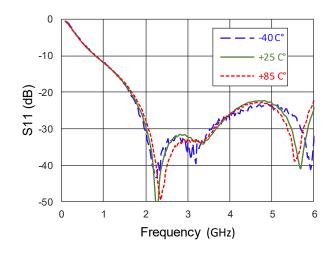


Typical Small-Signal Performance, Die On-Board: T_A = Over Temperature, Z_0 = 50 Ω

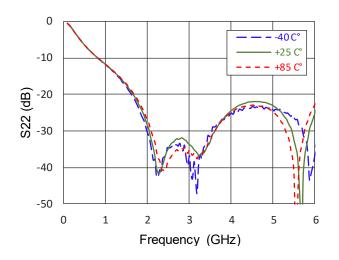
Insertion Loss



Input Return Loss



Output Return Loss

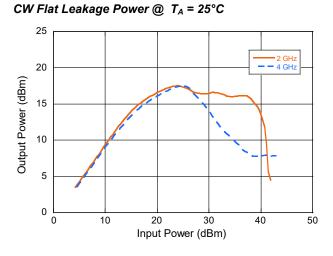


4

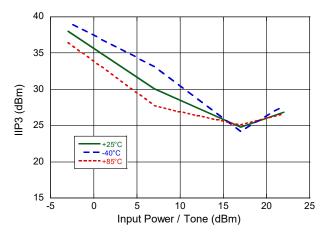


MADL-011173-DIE Rev. V1

Typical RF Power Performance, Die On-Board: $Z_0 = 50 \Omega$

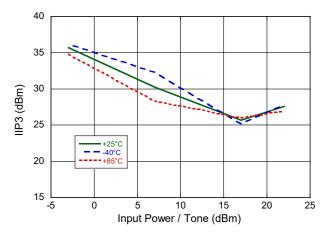


Input IP3 over Temperature @ 2 GHz



Input IP3 @ T_A = 25°C 40 2 GH 4 GH 35 (dBm) 30 <u>සි</u> 25 20 15 -5 0 10 15 20 25 5 Input Power (dBm)

Input IP3 over temperature @ 4 GHz

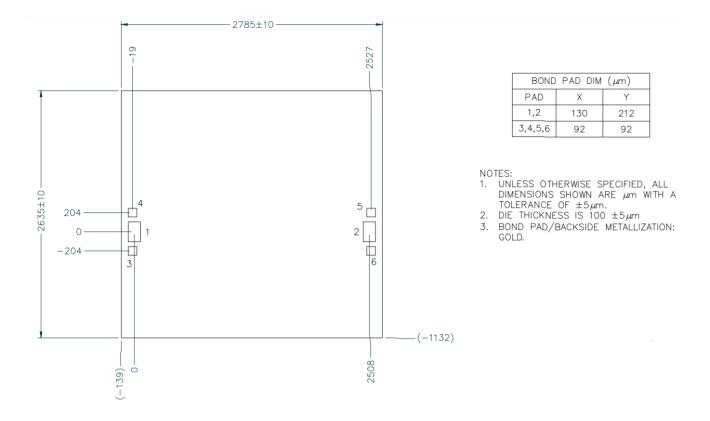


MACOM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit <u>www.macom.com</u> for additional data sheets and product information.



MADL-011173-DIE Rev. V1

Die Outline Drawing



Recommended Die Attachment

The die edge to die attach pad edge is recommended to be 5 mils minimum. High density solid Cu via farm or solid Cu heat slug is recommended under the attach pad for optimum thermal heat dissipation.

Eutectic die attachment is not recommended for this part. A high thermal conductivity epoxy shall be used. Voiding under the die should be minimized and no voiding should be present under the diode locations.

Wire Bonding Recommendation

For optimum bonding power handling performance and minimum bonding inductance, it is recommended to bond this part with two 3 x 0.5 mil gold ribbon wires on both the input and output RF pads. Low loop profile and minimum bond length are recommended.

For further information and support please visit: <u>https://www.macom.com/support</u>

⁶

MACOM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit <u>www.macom.com</u> for additional data sheets and product information.



MACOM Technology Solutions Inc. ("MACOM"). All rights reserved.

THESE MATERIALS ARE PROVIDED "AS IS" WITH NO WARRANTY OR LIABILITY, EXPRESS OR IMPLIED, RELATING TO SALE AND/OR USE OF MACOM PRODUCTS INCLUDING FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, INFRINGEMENT OF INTELLECTUAL PROPERTY RIGHT, ACCURACY OR COMPLETENESS, OR SPECIAL, INDIRECT, INCIDENTAL, OR CONSEQUENTIAL DAMAGES WHICH MAY RESULT FROM USE OF THESE MATERIALS.

MACOM products are not intended for use in medical, lifesaving or life sustaining applications. MACOM customers using or selling MACOM products for use in such applications do so at their own risk and agree to fully indemnify MACOM for any damages resulting from such improper use or sale.

These materials are provided in connection with MACOM's products as a service to its customers and may be used for informational purposes only. Except as provided in its Terms and Conditions of Sale or any separate agreement, MACOM assumes no liability or responsibility whatsoever, including for (i) errors or omissions in these materials; (ii) failure to update these materials; or (iii) conflicts or incompatibilities arising from future changes to specifications and product descriptions, which MACOM may make at any time, without notice. These materials grant no license, express or implied, to any intellectual property rights.

⁷

MACOM Technology Solutions Inc. (MACOM) and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice. Visit <u>www.macom.com</u> for additional data sheets and product information.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for PIN Diodes category:

Click to view products by MACOM manufacturer:

Other Similar products are found below :

 MA45471
 APD1520-000
 APD2220-000
 BAR 63-02L E6327
 BAR 64-02EL E6327
 BAR 90-02ELS E6327
 APD0810-000
 MA4L032-186

 MA4P606-258
 MA4P7435NM-1091T
 MA4PK2000
 MA4PK2001
 MA4PK2002
 MA4PK2003
 MA4PK2004
 MADP-030025-13140P
 BAR

 65-02V H6327
 MA4PBL027
 MA4P404-30
 MA4AGFCP910
 MA4P7101F-1072T
 MA4L022-30
 MA47047-54
 CLA4610-000
 UM9301SM

 5082-3077
 MADP-000502-12700P
 MA4P7493-134
 MA4L011-1088
 SMP1321-000
 UM4010SM
 UM7006B
 MADP-000015-000030

 MPP4203-206
 MPS2R10-606
 MPP4205-206
 GC40605-15
 MA4L021-1056
 MSWSE-050-17
 MADP-007455-0287DT
 MADP-007448

 1146DT
 MA4P929-401
 MA4P7455-287T
 LM200802-M-A-300-T
 MADP-010633-13920T
 MADP-007436-0287DT

 BAR6503WE6327HTSA1
 MADP-007433-0287HT
 MPL4702-406/TR
 MPL4703-406/TR